

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CJ02 Series Board Mound Telephone Jack	SPEC.NO.: SPCJ005E
REVISIONS	ECNT120188		PAGE: 1/3

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202 Methods for test of connectors for electronic equipment
EIA - 364 Test methods for electrical connectors

3. APPLICABLE SERIES NO.: CJ02 Series

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 1.6 mm (.063")

6.2 P.C. Board Layout: See attached drawings

REVIEWED : Eisley APPROVED : Sun VERIFIED : Michelle .



ENGINEERING DEPT.		PRODUCT SPECIFICATION For CJ02 Series Board Mound Telephone Jack	SPEC.NO.: SPCJ005E
REVISIONS	ECNT120188		PAGE: 2/3

7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1.5A 125V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 500 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Mating force	Measure force to mate samples at speed 25±3mm per minute with plug latch depressed	2.27 Kgf (5 lb) max.
8.2	Retention force (Between the jack and plug)	Retention speed 25±3mm per minute from jack	7.7 Kgf (17 lb) min.
8.3	Durability	Connector shall be subjected to 300 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Vibration	1.5 mm 10 - 55 - 10 HZ/minute each 2 hours for X,Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.2	Solder ability	Soldering time: 5±0.5 second Soldering pot: 230± 5°C	Minimum: 90% of immersed area
9.3	Resistance to soldering heat	Soldering time: 5±0.5 second Soldering pot: 260±5°C	No damage
9.4	Heat aging	105±2°C, 96 hours	No damage
9.5	Humidity	40±2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3



ENGINEERING DEPT.		PRODUCT SPECIFICATION For CJ02 Series Board Mound Telephone Jack	SPEC.NO.: SPCJ005E
REVISIONS	ECNT120188		PAGE: 3/3

	ITEM	TEST CONDITION	REQUIREMENT
9.6	Temperature cycling	<p>One cycle consists of :</p> <p>(1) $-55 \begin{smallmatrix} +0 \\ -3 \end{smallmatrix}^{\circ}\text{C}$, 30 min.</p> <p>(2) Room temp. 10-15 min.</p> <p>(3) $85 \begin{smallmatrix} +3 \\ -0 \end{smallmatrix}^{\circ}\text{C}$, 30 min.</p> <p>(4) Room temp. 10-15 min.</p>	<p>Appearance: No damage</p> <p>Contact resistance: Less than twice of initial</p>
9.7	Salt spray	<p>Temperature: $35 \pm 3^{\circ}\text{C}$</p> <p>Solution: $5 \pm 1\%$</p> <p>Spray time: 48 ± 4 hours (Stamping before plated)</p> <p>Spray time: 24 ± 4 hours (Stamping after plated)</p> <p>Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed.</p> <p>The specimens shall be suspended from the top using waxed twine, string or nylon thread.</p> <p>The test only define the plating area, without plating area (as copper cross section) will not be defined.</p> <p>(EIA 364-26B / MIL-STD-202 Method 101)</p>	<p>Appearance: No damage on function</p> <p>Contact resistance: Less than twice of initial</p>

10. AMBIENT TEMPERATURE RANGE: -40 to $+105^{\circ}\text{C}$